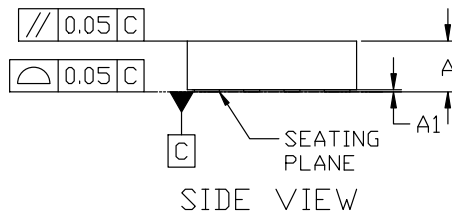
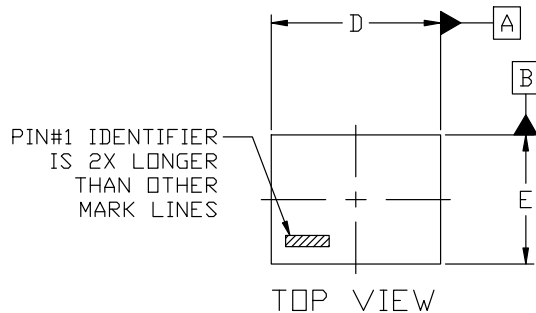


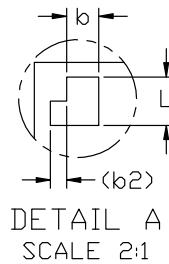
UQFN10 2.10x1.60x0.63, 0.50P
CASE 523AD
ISSUE O

DATE 02 JAN 2024

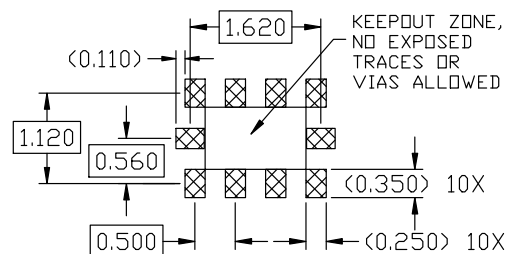
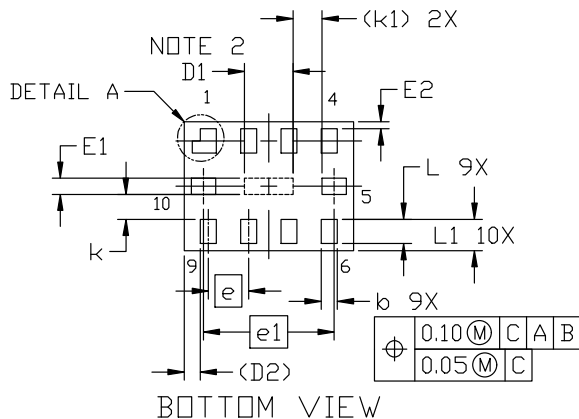


NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. PRESENCE OF CENTER PAD IS PACKAGE SUPPLIER DEPENDENT. IF PRESENT IT IS NOT INTENDED TO BE SOLDERED AND HAS A BLACK OXIDE FINISH.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.58	0.63	0.68
A1	0.00	---	0.05
b	0.15	0.20	0.25
b2	0.05	---	---
D	2.00	2.10	2.20
D1	0.55	0.60	0.65
D2	0.20 REF.		
E	1.50	1.60	1.70
E1	0.15	0.20	0.25
E2	0.00	---	0.15
e	0.50 BSC		
e1	1.62 BSC		
k	0.20	---	---
k1	0.36 REF.		
L	0.25	0.30	0.35
L1	0.25	---	0.42



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

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DESCRIPTION:	UQFN10 2.10x1.60x0.63, 0.50P	PAGE 1 OF 1

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